PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMCS1123A1AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A1A
TMCS1123A1AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A1A
TMCS1123A2AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A2A
TMCS1123A2AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A2A
TMCS1123A3AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A3A
TMCS1123A3AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A3A
TMCS1123A4AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A4A
TMCS1123A4AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A4A
TMCS1123A5AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A5A
TMCS1123A5AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123A5A
TMCS1123B1AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B1A
TMCS1123B1AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B1A
TMCS1123B2AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B2A
TMCS1123B2AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B2A
TMCS1123B3AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B3A
TMCS1123B3AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B3A
TMCS1123B4AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B4A
TMCS1123B4AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B4A
TMCS1123B5AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B5A
TMCS1123B5AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123B5A
TMCS1123C1AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C1A
TMCS1123C1AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C1A
TMCS1123C2AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C2A
TMCS1123C2AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C2A
TMCS1123C3AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C3A
TMCS1123C3AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C3A
TMCS1123C4AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C4A
TMCS1123C4AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C4A
TMCS1123C5AQDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C5A

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMCS1123C5AQDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123C5A
TMCS1123D71QDVGR	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123D71
TMCS1123D71QDVGR.A	Active	Production	SOIC (DVG) | 10	2000 | LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-40 to 125	1123D71

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TMCS1123 :

- Automotive : TMCS1123-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects